

Title (en)

Micro mechanical component and production process thereof.

Title (de)

Mikromechanisches Bauelement und Verfahren zur Herstellung desselben.

Title (fr)

Composant micromécanique et procédé pour sa fabrication.

Publication

EP 0674181 A3 19970205 (EN)

Application

EP 95104148 A 19950321

Priority

JP 5404794 A 19940324

Abstract (en)

[origin: EP0674181A2] A micro mechanical component of the present invention comprises a base, and at least one drive portion supported on the base and relatively driving to the base, in which the drive portion is formed from a diamond layer. Thus, because the drive portion has excellent mechanical strength and modulus of elasticity, the operational performance can be greatly improved as a micro mechanical component processed in a fine shape, from the conventional level. Further, because the drive portion exhibits excellent device characteristics under severe circumstances, the range of applications as a micro mechanical component can be widely expanded from the conventional range. <IMAGE>

IPC 1-7

G01P 15/08; **G01L 1/18**

IPC 8 full level

B81B 3/00 (2006.01); **B81C 1/00** (2006.01); **G01C 19/56** (2006.01); **G01H 3/08** (2006.01); **G01H 11/00** (2006.01); **G01H 11/06** (2006.01); **G01L 9/00** (2006.01); **G01P 15/08** (2006.01); **G01P 15/125** (2006.01); **G01Q 70/14** (2010.01)

IPC 8 main group level

G01Q 80/00 (2010.01)

CPC (source: EP US)

B81B 3/007 (2013.01 - EP US); **B81C 1/0015** (2013.01 - EP US); **B81C 1/00682** (2013.01 - EP US); **G01H 3/08** (2013.01 - EP US); **G01H 11/00** (2013.01 - EP US); **G01H 11/06** (2013.01 - EP US); **G01P 15/0802** (2013.01 - EP US); **G01P 15/125** (2013.01 - EP US); **B81B 2201/0235** (2013.01 - EP US); **B81B 2201/0264** (2013.01 - EP US); **B81B 2201/034** (2013.01 - EP US); **B81B 2201/035** (2013.01 - EP US); **B81B 2201/054** (2013.01 - EP US); **B81B 2203/0118** (2013.01 - EP US); **B81B 2203/04** (2013.01 - EP US); **B81C 2201/0109** (2013.01 - EP US); **G01P 2015/0828** (2013.01 - EP US)

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Designated contracting state (EPC)

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